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3 Characteristics

Forward current	I_f	30	mA
Reverse voltage	V_r	5	V
Power dissipation	P_d	110	mW
Operating temperature range	T_{op}	-25 +80	C
Storage temperature range	T_{stg}	-30 +80	C
Peak pulsed current 1/8 d f=1KH	I_{fp}	125	mA

Wavelength peak emission	$I_f=20mA$	peak	620	630	635	nm
Spectral half bandwidth	$I_f=20mA$			10		
Forward voltage	$I_f=20mA$	V_f	1.8	2.0	2.4	V
Minimum luminous intensity	$I_f=20mA$	I	1300	1650	2000	mcd



Viewing angle at 50% IV	If=10mA	--	120	--	Deg
Reverse current	Vr=5V	Ir	--	5	A
Useful life	-	IF=20mA	100000		H

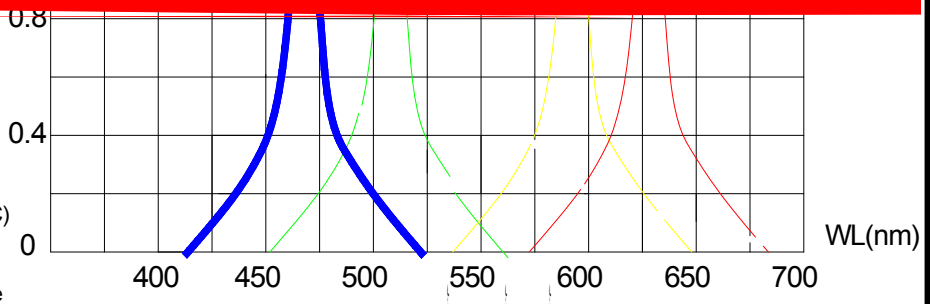
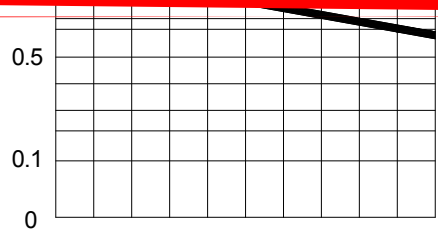
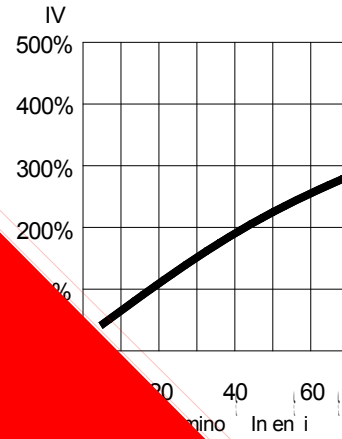
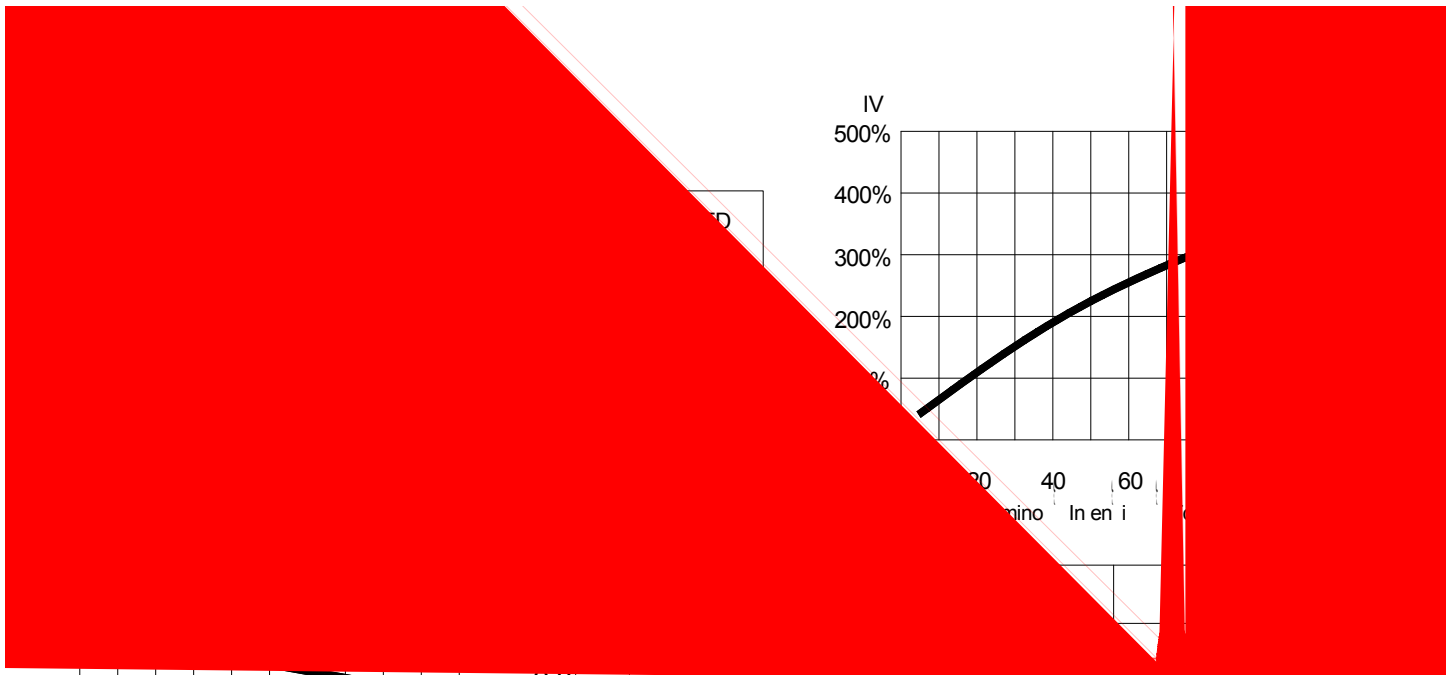
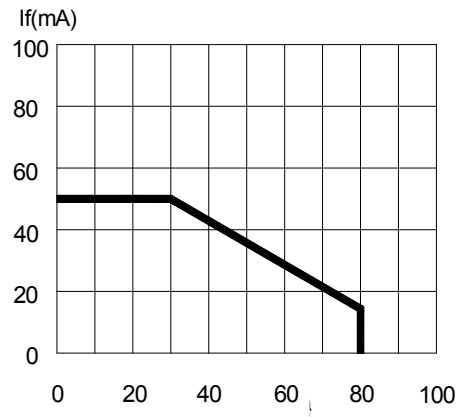


Fig.3 Relasi Intensity vs Ambient Temperature

Fig.4 Relasi Intensity vs Wavelength



- █ RED
- █ Blue
- █ Green
- █ Yellow
- █ White

Direct Characteristic

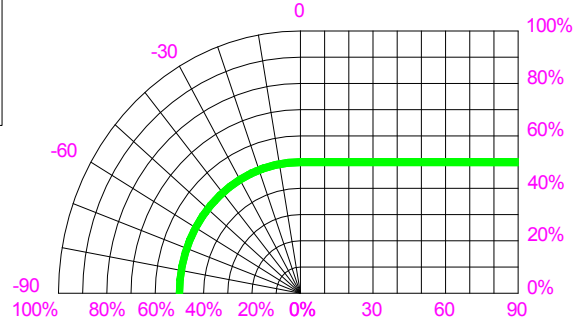


Fig.5 Maximum Forward Current vs Ambient Temperature



1	Tin-plated	Temp 260 ± 5	5 sec.	76 PCS	0/1
2	Back & forth under high & low temp. in general	High emp. +85 30min to 5min to -55 30min	50 bo	76 PCS	0/1
3	Heating	High emp. +100 30min To 10 sec to -10 30min	50 bo	76 PCS	0/1
4	High temp.	Temperature 100	1000 Hr.	76 PCS	0/1
5	Low temp.	-55	1000 Hr.	76 PCS	0/1
6	Life span	VF=1.9V IF=20mA	1000 Hr.	76 PCS	0/1
7	Test under high temp. & high humidity	85 °C /85%RH	1000 Hr.	76 PCS	0/1

i Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, soldering time 3 seconds, soldering position minimum 2mm from board.

ii Dip Soldering: Max temperature is 260 °C, time 5s, the position is minimum 2mm from board.

i Bracket must be bent only 2mm from colloid.

ii Bracket mold must be finished by fire or professional.

iii Bracket mold must be finished before soldering.

i Bracket mold holder are the connection between the pin, the distance gap of lead and the circuit board.

i. It should be paid attention to the ordering of all the devices in case of wrong polarity. Devices can be overloaded on the heat component, working condition can reduce the life.

ii. It should not assemble LED when the lead are deformed.

iii. When decide on a hole, accurately according to the size of hole and hole distance of the line board.

i. Suggesting good heating position

i. It should avoid any kind of shake or force on LED, before the soldering temperature return normal.

It should be careful. When clean the board with chemical. Some chemical may bring damage to the surface, and bring color fading, such as, Trichloroethylene, Acetone. Should use ethanol or isopropyl alcohol, dip for no more than 3 minutes under the normal temperature.

